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IBM and ZEON CORPORATION to collaborate on innovative PCBs for next-generation mainframe computer

ZEON CORPORATION (Tokyo Exchange: 4205.T) announced that it has signed an agreement with International Business Machines Corporation (NYSE: IBM) to jointly develop innovative printed circuit boards (PCBs) that enable Ultra-High-Speed Serial Links operating in excess of 25Gbps, for next-generation servers and mainframe computers.

Rapid growth of cloud computing and social network services has created increased demand for servers and PCB materials that are capable of increased information-processing capability.

In collaboration with IBM, the market and technology leader for mainframe computers and servers, significant synergetic effects can be expected using ZEON's new PCB materials, ZEONIF™ XL-Series, to overcome a number of current technological difficulties plaguing ultra-high-speed serial links. Under this agreement, ZEON engineers will work together with IBM engineers and researchers at IBM's Thomas J. Watson R&D Center, located in Yorktown Heights, NY USA.

**For further information
ZEON CORPORATION
Communication & Public Affairs
Tel: +81-3-3216-2747**